Abstract

This paper presents an overview of years of sensor system development and application for aerospace systems. The emphasis of this work is on developing advanced capabilities for measurement and control of aeropropulsion and crew vehicle systems as well as monitoring the safety of those systems. Specific areas of work include chemical species sensors, thin film thermocouples and strain gages, heat flux gages, fuel gages, SiC based electronic devices and sensors, space qualified electronics, and MicroElectroMechanical Systems (MEMS) as well as integrated and multifunctional sensor systems. Each sensor type has its own technical challenges related to integration and reliability in a given application. The general approach has been to develop base sensor technology using microfabrication techniques, integrate sensors with “smart” hardware and software, and demonstrate those systems in a range of aerospace applications. Descriptions of the sensor elements, their integration into sensors systems, and examples of sensor system applications will be discussed. Finally, suggestions related to the future of sensor technology will be given. It is concluded that smart micro/nano sensor technology can revolutionize aerospace applications, but significant challenges exist in maturing the technology and demonstrating its value in real-life applications.
AEROSPACE SENSOR SYSTEMS: FROM SENSOR DEVELOPMENT TO VEHICLE APPLICATIONS

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Sensors And Electronics Branch
NASA Glenn Research Center
Cleveland, OH
Sensors and Electronics Branch: Scope of Work

- High Temperature SiC Electronics
- Micro-electromechanical Systems (MEMS)
- Nanotechnology
- Chemical Sensors
- Thin Film Sensors
A RANGE OF SENSOR AND SENSOR SYSTEM DEVELOPMENT

HARSH ENVIRONMENT SENSORS AND ELECTRONICS

NASA GRC/CWRU O2 MICROSSENSOR
MICROSYSTEMS TECHNOLOGY

- THIS PRESENTATION DISCUSSES A RANGE OF GAS SENSOR TECHNOLOGY
- EXAMPLES REVOLVE AROUND MICROSYSTEMS TECHNOLOGY
- EXAMPLES INVOLVE AEROSPACE APPLICATIONS BUT HAVE BROADER IMPLICATIONS
- BASIC APPROACH: DRIVE CAPABILITIES TO THE LOCAL LEVEL/DISTRIBUTED SMART SYSTEMS

Microsystem Block Diagram

- Sensors: Physical/Chemical Signal
- Actuators: Mechanical/Display/Electrical Power
- Communication: Electrical/Optical
- Power: Analog-Digital-Analog Signal Processing
Improve system **reliability**, **cost**, and **weight** by using **local avionics elements** for distributed, smart sensing and control. Link local nodes to areas, then integrate entire vehicle using hierarchical design.

**Localized Avionics System Infrastructure**

- **Controller**
- **Component**
- **Link**
- **Component**

**HiTemp electronics**
- Rad hard electronics
- Distributed control
- Algorithms
- Self-diagnosing
- Self-calibrating
- Hierarchical control
- Signal/data conditioning

**HiTemp electronics**
- Embedded sensors
- Microsensors
- Optical Actuation
- Electronic actuation

**Connector**
- Switch
- Multiplexer
- Harness
- Transmitter
- Detector

**Copper wire**
- Optical fiber
- Telemetry
- Radio frequency
- Optical free-space

**Connector**
- Switch
- Multiplexer
- Harness
- Transmitter
- Detector

**Vehicle**
- **Node**
- **Area**
- **Node**
- **Node**
HARSH ENVIRONMENT ELECTRONICS AND SENSORS APPLICATIONS

• NEEDS:
  ➢ OPERATION IN HARSH ENVIRONMENTS
  ➢ RANGE OF PHYSICAL AND CHEMICAL MEASUREMENTS
  ➢ INCREASE DURABILITY, DECREASE THERMAL SHIELDING, IMPROVE IN-SITU OPERATION

• RESPONSE: UNIQUE RANGE OF HARSH ENVIRONMENT TECHNOLOGY AND CAPABILITIES
  ➢ STANDARD 500C OPERATION BY MULTIPLE SYSTEMS
  ➢ TEMPERATURE, PRESSURE, CHEMICAL SPECIES, WIND AVAILABLE
  ➢ HIGH TEMPERATURE ELECTRONICS TO MAKE SMART SYSTEMS

• ALL-IN-ONE SHOP FOR HARSH ENVIRONMENT SYSTEM APPLICATIONS

• ENABLE EXPANDED MISSION PARAMETERS/IN-SITU MEASUREMENTS

Range of Physical and Chemical Sensors for Harsh Environments
Harsh Environment Packaging (7000 hours at 500C)
High Temperature Signal Processing and Wireless
Long Term: High Temperature “Lick and Stick” Systems
“LICK AND STICK” TECHNOLOGY (EASE OF APPLICATION)
- Micro and nano fabrication to enable multipoint inclusion of sensors, actuators, electronics, and communication throughout the vehicle without significantly increasing size, weight, and power consumption. Multifunctional, adaptable technology included.

RELIABILITY:
- Users must be able to believe the data reported by these systems and have trust in the ability of the system to respond to changing situations e.g. decreasing sensors should be viewed as decreasing the available information flow about a vehicle. Inclusion of intelligence more likely to occur if it can be trusted.

REDUNDANCY AND CROSS-CORRELATION:
- If the systems are easy to install, reliable, and do not increase weight/complexity, the application of a large number of them is not problematic allowing redundant systems, e.g. sensors, spread throughout the vehicle. These systems will give full-field coverage of the engine parameters but also allow cross-correlation between the systems to improve reliability of sensor data and the vehicle system information.

ORTHOGONALITY:
- Systems should each provide a different piece of information on the vehicle system. Thus, the mixture of different techniques to “see, feel, smell, hear” as well as move can combine to give complete information on the vehicle system as well as the capability to respond to the environment.
OUTLINE

• INTRODUCTION

• SENSOR ELEMENT
  ➢ TECHNOLOGIES AND CHALLENGES

• MICROFABRICATED GAS SENSORS
  ➢ SENSOR PLATFORMS
  ➢ SMART SENSORS SYSTEMS AND DEMONSTRATIONS

• SUPPORTING TECHNOLOGIES
  ➢ HIGH TEMPERATURE ELECTRONICS EXAMPLE

• SYSTEM APPLICATION
  ➢ MATURATION FOR ISS APPLICATIONS
  ➢ SPACE QUALIFIED ELECTRONICS AND SENSORS
  ➢ MOBILE SENSOR PLATFORMS

• SENSOR DATA QUALIFICATION

• FUTURE DIRECTIONS
  ➢ NANOTECHNOLOGY

• SUMMARY
SENSOR ELEMENTS:

SPACE APPLICATIONS AND TECHNICAL CHALLENGES

TAILOR THE SENSOR TO THE APPLICATION
Thin Film Physical Sensors for High Temperature Applications

Advantages for temperature, strain, heat flux, flow & pressure measurement:

♦ Negligible mass & minimally intrusive (microns thick)
♦ Applicable to a variety of materials including ceramics
♦ Minimal structural disturbance (minimal machining)
♦ Intimate sensor to substrate contact & accurate placement
♦ High durability compared to exposed wire sensors
♦ Capable for operation to very high temperatures (>1000°C)

Multifunctional smart sensors being developed

- PdCr strain sensor to T=1000°C
- Pt- Pt/Rh temperature sensor to T=1200°C
- Heat Flux Sensor Array to T=1000°C
- Multifunctional Sensor Array
GRC’s Physical Sensor Instrumentation
Research History

- NASA Group Achievement Award 2003
- Partnerships in Sensor Development:
  - Rolls-Royce, GE Aircraft Engines, Pratt & Whitney
  - Goodyear Tire & Rubber Company
  - University of Rhode Island
  - Air Force Research Lab (NDE Branch)

2003 NASA Group Achievement Award
SiC High Temperature Drag Force
Transducer as part of the Integrated
Instrumentation and Testing Systems project

1991 R&D 100 Award
PdCr wire strain gauge applied on
Ford Motor Co. exhaust manifold

1995 R&D 100 Award
PdCr thin film gauge applied on Allied-Signal
Engines ceramic turbine blade

1998 R&D 100 Award
Long-lived Convoluted Thermocouples
For Ceramic Temperature Measurements
Novel Thin Film Sensor Technology Development

• Development of Thin Film Sensors with Ceramic, Laminate and Nanostructured Materials
  - Improve techniques for applying high temperature sensors onto complex structures
  - Develop thin film sensors to measure temperature, strain, and heat flux for hot section components

• Technology Challenge: Survivability in Extremely High Temperature Environments (>1500°C)
  - Build off of experience fabricating devices on more conventional components
  - Leverage partnerships with University of Rhode Island and NASA GRC Ceramics Branch for ceramic-based materials
CEV Interface Seals Instrumentation

Thermal Protection System (TPS) Interface Seals
- Instrumentation for Interface Gap Heating Tests for CEV Heat Shield-to-Backshell Interface Seals
  - Design, fabrication and testing of a packaged miniature heat flux sensor
- Technology Challenge: Sensor Integration with Packaging
  - Leverage RTD Heat Flux Sensor development & Novel Thin Film Sensor effort

Low Impact Docking System (LIDS) Interface Seals
- Instrumentation to Measure Pressure Between Two Seal Bulbs
  - Concept design, model and lab demonstration of pressure sensor
- Technology Challenge: Sensor Integration with Tight Size Tolerance
  - Miniature size so as to not interfere with the sealing function

LIDS Pressure Sensor Concept Location

LIDS Pressure Sensor Concept Modeled

LIDS Pressure Sensor Sensitivity vs. Air Pressure
Advanced Stirling Convertor (ASC) Sensors

- Development of Heat Flux Sensors for ASC Units for measurement of thermal energy delivered into the converter
  - Allows for a direct measurement of thermal to electrical conversion efficiency in characterizing the ASC units
- Technical Challenge: Sensor Fabrication Methods Compatible with ASC Thermal and Structural Demands
  - Sensor Thermal Conductivity, Strength and Sensitivity satisfied with High Temperature Ceramics

Venus Rover Concept with ASC Cooling

ASRG Engineering Unit with Planned Location of Heat Flux Sensors

ASC-E Convertor

Heat Flux Sensor Design being Fabricated at NASA GRC

Glenn Research Center
Propellant gauging sensor

Radio Frequency Mass Gauge (RFMG)

- Detects electromagnetic modes of a tank using an antenna and RF analyzer
- Mode frequencies are affected in a known way by liquid quantity
- Applicable to dielectric liquids such as liquid hydrogen, oxygen, methane.
- Tests in 58 cu. ft. liquid oxygen tank indicate high accuracy. RMS gauging uncertainty <1% full-scale.
- RFMG is being developed in-house at NASA GRC
- Potential application to EDS and Altair tanks
- Currently at TRL-5

POC: Greg.Zimmerli@nasa.gov
Future work is designed to push development of the RFMG to TRL 6-7.

<table>
<thead>
<tr>
<th>Risk</th>
<th>Mitigation Plan</th>
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<tbody>
<tr>
<td>Unknown RFMG performance in larger scale tanks, and with other internal hardware.</td>
<td>Construct a full-scale mock LH2 Lander tank and test RF response with internal hardware (no cryo-fluid).</td>
</tr>
<tr>
<td>A high-fidelity flight-prototype instrument unit has never been tested.</td>
<td>Initiate development of a 2nd generation Engineering Model. Goal is to meet typical thermal, vacuum, vibe, EMI spec’s (will try to mimic spec’s on Orion CEV).</td>
</tr>
<tr>
<td>The structural integrity of the antenna and RF connections has not been determined.</td>
<td>Need to identify/test appropriate connectors. Need to design &amp; vibe-test flight-like antenna.</td>
</tr>
<tr>
<td>Performance in low-gravity is uncertain.</td>
<td>1g tilted tank tests. Possible low-gravity aircraft testing. Simulations.</td>
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SiC-BASED PRESSURE SENSORS

• SiC HAS EXCELLENT MECHANICAL PROPERTIES FOR USE AS A HARSH ENVIRONMENT PRESSURE SENSOR (T > 500 °C, SILICON UNDERGOES PLASTIC DEFORMATION)

• FORM DIAPHRAM OF SiC AND INTEGRATE WITH ELECTRONICS

• WIDE RANGE OF APPLICATIONS
  ➢ AERONAUTIC ENGINE APPLICATIONS
  ➢ AUTOMOTIVE APPLICATIONS
  ➢ WIND TUNNELS
  ➢ MATERIAL PROCESSING

• ENGINE OPERATION DEMONSTRATED AT 500 °C

• TECHNICAL CHALLENGES INCLUDE
  ➢ SiC DIAPHRHAM FORMATION (ETCHING)
  ➢ PACKAGING
  ➢ RELIABILITY TESTING
SENSOR PLATFORMS TO SMART SENSOR SYSTEMS:
MICROFABRICATED GAS SENSORS
MICROFABRICATED GAS SENSORS

- COLLABORATIVE EFFORT BETWEEN NASA GRC, CASE WESTERN RESERVE, and OHIO STATE UNIVERSITY

- SENSOR DEVELOPMENT RESULTING FROM:
  IMPROVEMENTS IN MICROFABRICATION AND MICROMACHINING TECHNOLOGY
  NANOMATERIALS
  DEVELOPMENT OF SiC-BASED SEMICONDUCTOR TECHNOLOGY

- GAS DETECTION IN:
  HARSH ENVIRONMENTS
  APPLICATIONS BEYOND CAPABILITIES OF COMMERCIAL SENSORS

- TECHNOLOGY DEVELOPS PLATFORMS FOR A VARIETY OF MEASUREMENTS
  SCHOTTKY DIODE
  RESISTANCE BASED
  ELECTROCHEMICAL

- TARGET DETECTION OF GASES OF FUNDAMENTAL INTEREST
  HYDROGEN (H₂)
  HYDROCARBONS (CₓHᵧ)
  NITROGEN OXIDES (NOₓ) AND CARBON MONOXIDE (CO)
  OXYGEN (O₂)
  CARBON DIOXIDE (CO₂)
BASE PLATFORM SENSOR TECHNOLOGY
Integration of Micro Sensor Combinations into Small, Rugged Sensor Suites
Example Applications: AEROSPACE VEHICLE FIRE, FUEL LEAKS, EMISSIONS, ENVIRONMENTAL MONITORING CREW HEALTH, SECURITY

Multi Species Fire Sensors for Aircraft Cargo Bays and Space Applications
Environmental monitoring (ISS Whitesand Testing)
“Lick and Stick” Space Launch Vehicle Leak Sensors with Power and Telemetry
Aircraft Propulsion Exhaust High Temperature Electronic Nose
Sensor Equipped Prototype Medical Pulmonary Monitor
Hydrazine EVA Sensors (ppb Level Detection)

Oxygen Sensor
SiC Hydrocarbon Sensor
Nanocrystalline Tin Oxide NOx and CO Sensor
H2 Sensor
HYDROGEN LEAK SENSOR TECHNOLOGY

- MICROFABRICATED USING MEMS-BASED TECHNOLOGY FOR MINIMAL SIZE, WEIGHT AND POWER CONSUMPTION

- HIGHLY SENSITIVE IN INERT OR OXYGEN-BEARING ENVIRONMENTS, WIDE CONCENTRATION RANGE DETECTION

- TWO SENSOR SYSTEM FOR FULL RANGE DETECTION: FROM PPM LEVEL TO 100%
HYDROGEN LEAK SENSOR TECHNOLOGY

• STATUS: OPERATIONAL SYSTEM ON ISS WITH ASSOCIATED HARDWARE
• BEING PREPARED FOR CLV IMPLEMENTATION

1995 R&D 100 AWARD WINNER

NASA 2003 TURNING GOALS INTO REALITY SAFETY AWARD

Shuttle  X33  X43  Helios  ISS

SiC-BASED GAS SENSOR DEVELOPMENT

• THE USE OF SiC SEMICONDUCTORS ALLOWS SENSOR OPERATION AT TEMPERATURES WHICH ALLOW THE DETECTION OF HYDROCARBONS AND NOx

• INERT MATERIAL OPERATIONAL IN HIGH TEMPERATURE, CORROSIVE ENVIRONMENTS

• SCHOTTKY DIODE DESIGN FOR HIGH SENSITIVITY

• TEMPERATURE DETECTOR AND HEATER INCLUDED/OPERATION AT A RANGE OF TEMPERATURES

• WIDE RANGE OF APPLICATIONS
  EMISSION MONITORING
  ENGINE HEALTH MONITORING
  ACTIVE COMBUSTION CONTROL
  HYDROCARBON FUEL LEAK DETECTION
  FIRE SAFETY

• PROTOTYPE SENSOR PACKAGE FABRICATED/TESTED IN ENGINE ENVIRONMENTS

• APPROACHES
  ALLOY ON SiC SUBSTRATE
  REACTIVE INSULATOR APPROACH
  BARRIER LAYER
  ATOMICALLY FLAT SiC
MICROFABRICATED OXYGEN SENSOR TECHNOLOGY

- MICROFABRICATED AND MICROMACHINED FOR MINIMAL SIZE, WEIGHT AND POWER CONSUMPTION (NEAR 100 mW FOR ~500°C OPERATION)

- AMPEROMETRIC OPERATION ALLOWS MEASUREMENT OF OXYGEN OVER A WIDE CONCENTRATION RANGE (0-100%)

- CHAMBER STRUCTURE CONTROLS OXYGEN DIFFUSION RATE

- RELATIVELY MATURE TECHNOLOGY/PACKAGING COULD BE IMPROVED TO DECREASE POWER CONSUMPTION

ZrO2 Oxygen Sensor Response To Various Oxygen Concentrations

Not to scale:
MICROFABRICATED TIN OXIDE BASED NOx AND CO SENSOR TECHNOLOGY

- MICROFABRICATED FOR MINIMAL SIZE, WEIGHT AND POWER CONSUMPTION
- MICROMACHINED TO MINIMIZE POWER CONSUMPTION AND IMPROVE RESPONSE TIME
- TEMPERATURE DETECTOR AND HEATER INCORPORATED INTO SENSOR STRUCTURE
- NANOFABRICATION OF TIN-OXIDE TO INCREASE SENSOR STABILITY

50 Hp Gas Turbine

Industry Standard Continuous Emission Monitoring Equipment

REPLACE INSTRUMENT RACK SIZED SYSTEM WITH DIME SIZED SENSOR AND ACCOMPANYING ELECTRONICS
SENSOR SYSTEM DEVELOPMENT

• EACH SENSOR PLATFORM PROVIDES QUALITATIVELY VERY DIFFERENT TYPES OF INFORMATION ON THE ENVIRONMENT

• SENSOR ARRAY VARIES WITH APPLICATION/MICROFABRICATION TECHNIQUES MANDATORY

• BASIS CHEMICAL SENSOR FEATURES:
  ➢ RESPONSE TIME, SENSITIVITY, SELECTIVITY, STABILITY
  ➢ BATCH FABRICATION, PROCESSING REPRODUCIBILITY, CONTROL OF STRUCTURE
  ➢ TAILOR SENSOR SYSTEM FOR THE APPLICATION

• SUPPORTING TECHNOLOGIES NECESSARY
  ➢ PACKAGING (OFTEN UP TO 70% OF OVERALL SENSOR COST)
  ➢ SIGNAL CONDITIONING AND PROCESSING
  ➢ SOFTWARE (E.G. NEURAL NET PROCESSING, MODELING)
  ➢ POWER AND COMMUNICATION

MINIATURIZED SMART LEAK SENSOR SYSTEM

MICROFABRICATED HYDROGEN SENSOR

HYDROGEN SENSORS ON SPACE SHUTTLE

PROTOTYPE HYDROGEN/OXYGEN SENSOR SYSTEM WITH ELECTRONICS

DEMONSTRATE STAND-ALONE SMART LEAK DETECTION SYSTEM WITH A SURFACE AREA THE SIZE OF POSTAGE STAMP
“LICK AND STICK” LEAK SENSOR SYSTEM

• COMBINE FUEL (HYDROGEN, HYDROCARBON) WITH OXYGEN IN AN ARRAY: DETERMINE EXPLOSIVE COMBINATIONS
• SELF-CONTAINED SYSTEM WHICH CAN BE IMPLEMENTED WHEREVER, WHENEVER NEEDED WITHOUT REWIRING OR SIGNIFICANT POWER DRAIN TO THE VEHICLE
• ON-GOING ACTIVITY: DECREASE SIZE AND POWER OF SENSORS/ELECTRONICS

FIRST STEP: COMBINE SMALLER SENSORS WITH SMALLER, SMART ELECTRONICS

HYDROGEN SENSOR SIZE REDUCTION

HYDROGEN AND OXYGEN SENSORS PACKAGED ON SAME CHIP

MINIATURIZED ELECTRONICS

HYDROGEN SENSOR

OXYGEN SENSOR

MEI Makel Engineering Inc.

CWRU

Glenn Research Center
“Lick and Stick” Leak Sensor System

- Sensors, power, and telemetry self-contained in the near the size of a postage stamp
- Microprocessor included/smart sensor system
- Verify system compatibility with space applications
- Adaptable core system which can be used in a range of applications
- Multiple configurations available

“Lick and Stick” Leak Detection Electronics and Three Sensors

System configured with different wireless antennae.
“LICK AND STICK” LEAK SENSOR SYSTEM DEMONSTRATION

- WIRELESS DEMONSTRATION OF 3 SENSOR SYSTEM ACHIEVED
- BASELINE: ZIRCONIA BASED O2 SENSOR (ALTHOUGH NAFION BASED ROOM TEMPERATURE SYSTEM BEING MATURED FOR USE)
- LONGEVITY OF SENSOR SYSTEM LIFE ON A BATTERY IS A LIMITATION IN SOME APPLICATIONS
- MOVE FROM HIGH TEMPERATURE SENSOR TECHNOLOGY TO LOWER TEMPERATURE SENSORS
- BEING QUALIFIED FOR CREW LAUNCH VEHICLE APPLICATIONS (HARDWIRED) FOR HYDROGEN DETECTION ONLY
HIGH TEMPERATURE GAS SENSOR ARRAY
HIGH TEMPERATURE ELECTRONIC NOSE

SnO2 Resistor   TiO2 Resistor   Electrochemical Oxygen Sensor

Selectively Filtered SnO2 Resistors

Metal-SiC Schottky diodes   Metal-Reactive Insulator SiC Schottky diodes

SiC-Based Pressure Sensor

Makel Engineering, Inc.

Glenn Research Center
Harsh Environment Demonstration Testing

1.9 liter, four cylinder HCCI at U.C. Berkeley (propane/air)

- **Engine Start**
  - Expected Drop In O2 Signal
  - Rise in Unburned Hydrocarbons At Start Up And Throttle Adjustment

- **Steady Engine Operation**
  - Exhaust Gas Temperature = 337 C
  - Phi = 0.35
  - O2 = 14%
  - NOx < 5 PPM
  - CO = 1400 PPM
  - UHC = 1200 PPM

- **Engine Turned Off**

Makel Engineering, Inc.

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**Signal (mV)**

- Oxygen Sensor
- SnO2 Sensor
- SiC Hydrocarbon Sensor
MICRO SENSORS TESTED AT OUTLET OF THE JT-12 JET ENGINE

Rake Sampling System At The Outlet Of The JT-12 Jet Engine. Location Of The Sensors In The Flow Stream Of The Rake

HIGH TEMPERATURE OPERATIONAL CAPABILITY AN OF THE SENSORS ALLOW PLACEMENT SIGNIFICANTLY CLOSER TO THE ENGINE OUTLET THAN TRADITIONAL EQUIPMENT.
Micro-Fabricated Gas Sensors for Low False Alarms

FEATURES

- MICROFABRICATED CO/CO₂ GAS SENSOR ARRAY
  - AIM TO DECREASE FALSE ALARM RATE WHICH IS AS HIGH AS 200:1
  - CENTRAL TO APPROACH
  - NANOCRYSTALLINE MATERIALS (IN CO SENSOR) PRODUCE MORE SENSITIVE, STABLE SENSORS
  - TWO APPROACHES TO CO₂ DETECTION
  - MINIMAL SIZE/WEIGHT/POWER

- CHEMICAL GAS SENSORS PROVIDE GASEOUS PRODUCT-OF-COMBUSTION INFORMATION
  - SENSOR ARRAY CAN DETECT RANGE OF GAS SPECIES
  - TO BE COMBINED WITH INTELLIGENT SOFTWARE FOR PATTERN RECOGNITION

- BENEFITS
  - DISCRIMINATE FIRES FROM NON-FIRES

Current B757 Cargo Compartment Smoke Detection

Sampling Tubes

Air Sampling Ports
OVERALL FIRE DETECTION APPROACH FOR SPACE APPLICATIONS:

• COMBINED MEMS-BASED CHEMICAL SPECIES AND PARTICULATE
• ORTHOGONAL DETECTION AND CROSS-CORRELATION SIGNIFICANTLY REDUCES FALSE ALARMS
FAA Cargo Bay Fire Simulation Testing
Boeing 707 luggage compartment and the FAA “Biscuit”
FAA Cargo Bay Fire Testing
No False Alarms/Consistent Detection of Fires
Transitioning to Space Fire Applications

- RH
- CO
- H2/CxHy
- CO2
- IMS

**Legend:**
- PdCr-Diode-721 Sensor
- CO-165-diode Sensor
- CO2-179-res Sensor
- RH %
- IMS Volts

**Timeline:**
- Ignition
- Smoke Alarm
- NASA/MEI Alarm (fast)
- NASA/MEI Alarm (slow)
SUPPORTING TECHNOLOGIES

SUPPORTING TECHNOLOGIES OFTEN DETERMINE SUCCESS OF SYSTEM

HARSH ENVIRONMENT SYSTEMS
High Temperature Wireless Development

OBJECTIVES:
• HIGH TEMPERATURE WIRELESS TELEMETRY, DISTRIBUTED ELECTRONICS OVER A BROAD OPERATING RANGE

TECHNICAL CHALLENGES:
— DEVELOPMENT OF RELIABLE HIGH TEMPERATURE TELEMETRY ELECTRONICS, POWER SOURCES, REMOTE COMMUNICATION ELECTRONICS, AND PACKAGING

GOALS SUPPORTED:
— ENHANCE PERFORMANCE
— SIGNIFICANTLY REDUCE COST

PROVIDE DATA TRANSFER IN HARSH ENVIRONMENTS IMPROVING RELIABILITY AND ENABLING NEW CAPABILITIES

Example: Gas Turbine Engine Development Requires Extensive Instrumentation Yielding Extensive Wiring Complexity
Previous Key NASA Glenn Advancements

Key fundamental high temperature electronic materials and processing challenges have been faced and overcome by systematic basic materials processing research (fabrication and characterization).

500 °C Durable Metal-SiC Contacts
(R. Okojie, 2000 GRC R&T Report)

500 °C Durable Chip Packaging
And Circuit Boards
(L. Chen, 2002 GRC R&T Report)

Additional advancements in device design, insulator processing, etc. also made.
6H-SiC Junction Field Effect Transistor (JFET)
Fabricated by NASA Glenn Research Center

200µm/10µm 6H-SiC JFET

Multiple devices in Ceramic Packaging

Packaged with bond wires

Differential Amplifier

200µm/10µm 6H-SiC JFET
NASA Glenn Silicon Carbide Differential Amplifier

World’s First Semiconductor IC to Surpass 4000 Hours of Electrical Operation at 500 °C

Demonstrates CRITICAL ability to interconnect transistors and other components (resistors) in a small area on a single SiC chip to form useful integrated circuits that are durable at 500 °C.

Optical micrograph of demonstration amplifier circuit before packaging

2 transistors and 3 resistors integrated into less than half a square millimeter.

Single-metal level interconnect.

Test waveforms at 500 °C

Input (1 V P-P Sinewave)

Output 1 hr. @ 500 °C

Output 4000 hr. @ 500°C

Less than 5% change in operating characteristics during 4000 hours of 500 °C operation.
NASA Glenn SiC JFET NOR Gate IC

World’s First Semiconductor Digital IC to Surpass 2000 hours of 500°C Operation

Waveforms of packaged NOR (= “Not OR”) gate at 500°C

IN A

IN B

OUT A+B

Time at 500°C

1 hour

2015 hours
SIGNIFICANCE OF RECENT ELECTRONICS RESULTS
THE BASIC HARDWARE TOOLS FOR HIGH TEMPERATURE DATA PROCESSING
HAVE BEEN FABRICATED

♦ THESE RESULTS HAVE BEEN THE SUBJECT OF A HIGH LEVEL OF VISIBILITY
   E.G. NASA TOP 10 DISCOVERY STORIES FOR 2007

♦ DURABLE HIGH TEMPERATURE IC’S WILL ENABLE IMPORTANT NEW
   CAPABILITY
   
   ➢ Enabled by fundamental electronic materials research.
   
   ➢ World record IC durability at 500 °C (> 400-fold improvement).
   
   ➢ Inherently up-scalable to high circuit complexity while remaining physically small.

♦ THIS DEMONSTRATION SHOWS THAT IT IS NOW POSSIBLE TO CONSTRUCT
   MORE COMPLEX CIRCUITS OPERATING AT 500 °C AND MINIATURIZED.

♦ LOGIC GATES GENERATE FLIP-FLOPS THAT CAN GENERATE STATE-
   MACHINES TO ENABLE:
   
   ➢ Creation Of Control Electronics For An “Intelligent” Fixed Or Mobile Agent
   
   ➢ The Configuration Of Intelligent Data Transmission Methods Allowing For
     Unambiguous Demodulation Of Signals Uniquely Associated With Each
     Sensor/Transmitter In A Network.
OBJECTIVE: TO MOVE TOWARD HIGHER DEGREES OF COMPLEXITY
ALLOWING WIRELESS TRANSMISSION AND HARSH ENVIRONMENT
SMART SENSOR SYSTEMS

Overall Approach:
Smart Systems in High Temperature Environments
Milestone: Demonstrate High Temperature Sensing, Wireless Communication,
and Power Scavenging for Propulsion Health Management
8/30/2011
Metric: Demonstrate integrated self powered wireless sensor system at 500
C with data transmission with operational life of at least 1 hr

Significant wiring exists with present sensor systems

Allow Sensor Implementation by Eliminating Wires

World Record High Temperature Electronics Device Operation
High Temperature RF Components
Energy Harvesting Thin Film Thermoelectrics
SENSOR SYSTEM APPLICATION

SYSTEM TESTING TO MOBILITY
FUTURE APPLICATIONS
LICK AND STICK SYSTEMS
BRIEF LIST OF LAUNCH, IN-SPACE, AND LUNAR APPLICATIONS

LAUNCH
Propellant Leaks
Toxic Gas Leaks

IN-SPACE
Propellant Fuel Leaks
Toxic Gas Leaks
Environmental Monitoring
Fire Detection
EVA

LUNAR
Propellant Fuel Leaks
Toxic Gas Leaks
Environmental Monitoring
Fire Detection
EVA/ISRU Applications
SUMMARY
TOOLS TO ENABLE NEW MISSIONS

EXAMPLE POSSIBLE MISSION: Venus Integrated Weather Sensor (VIWS) System
Sensor Suite to Monitor Venus Weather Conditions including: Data Processing and Communication, Wind Flow, Seismic, Pressure/Temperature/Heat Flux, Chemical Environment

- HIGH TEMPERATURE ELECTRONIC NOSE (Chemical Species)
- HOTProbe (Wind flow, Pressure, Temperature)
- Hi-g SiC ACCELEROMETER (Seismic Activities)
- PRESSURE SENSOR (Pressure)
- SiC ELECTRONICS (Data Processing and Com)
- MULTIFUNCTIONAL PHYSICAL SENSOR ARRAY (Temperature, Heat Flux)
One Potential Vision: “Smart” Suit

- Development of a “Smart” Suit which has self-monitoring, caution and warning, and control capabilities with high levels of reliability, durability, and safety.
- Small, lightweight, low power sensor systems, with increased packaging flexibility, will improve the effectiveness and extensibility of the EVA suits.
- Seamless integration of sensors throughout EVA system improving reliability and capability without significantly increasing system wiring and power.
- Monitor Both Inside And Outside the EVA Suit for Astronaut Health and Safety/Suit Maintenance
  - **Inside:** For Example, Monitor Suit CO2, O2, Flow to Allow Metabolic Measurements
  - **Outside:** For Example, Monitor Dust/Toxic Gas/Dangerous Conditions Before Brought Back Into Airlock Or Can Affect Astronaut Safety
- Include Ability to Determine Astronaut Health by Monitoring of Breath

**A “Smart” Suit Needs To Monitor Both Internal And External Conditions**

**Breath Sensor System** — includes mouthpiece for breath collection, Nafion drying tube in sample line, sensor manifold with PDA interface, and mini sampling pump
SENSOR SYSTEM IMPLEMENTATION

• OBJECTIVE: A SELF-AWARE SYSTEM COMPOSED OF SMART COMPONENTS MADE POSSIBLE BY SMART SENSOR SYSTEMS

• SENSOR SYSTEMS ARE NECESSARY AND ARE NOT JUST GOING TO SHOW UP WHEN NEEDED/TECHNOLOGY BEST APPLIED WITH STRONG INTERACTION WITH USER

• SENSORS SYSTEM IMPLEMENTATION OFTEN PROBLEMATIC
  - LEGACY SYSTEMS
  - CUSTOMER ACCEPTANCE
  - LONG-TERM VS SHORT-TERM CONSIDERATIONS
  - SENSORS NEED TO BUY THEIR WAY INTO AN APPLICATION

• SENSOR DIRECTIONS INCLUDE:
  - INCREASE MINIATURIZATION/INTEGRATED INTELLIGENCE
  - MULTIFUNCTIONALITY/MULTIPARAMETER MEASUREMENTS/ORTHOGONALITY
  - INCREASED ADAPTABILITY
  - COMPLETE STAND-ALONE SYSTEMS (“LICK AND STICK” SYSTEMS)

• POSSIBLE LESSONS LEARNED
  - SENSOR SYSTEM NEEDS TO BE TAILORED FOR THE APPLICATION
  - MICROFABRICATION IS NOT JUST MAKING SOMETHING SMALLER
  - ONE SENSOR OR EVEN ONE TYPE OF SENSOR OFTEN WILL NOT SOLVE THE PROBLEM: THE NEED FOR SENSOR ARRAYS
  - SUPPORTING TECHNOLOGIES OFTEN DETERMINE SUCCESS OF A SYSTEM
ROOM TEMPERATURE O2 SENSOR TECHNOLOGY

• POSSIBLE REPLACEMENT FOR PRESENT LIQUID ELECTROCHEMICAL CELL TECHNOLOGY

• VIABILITY FOR SPACE BASED APPLICATIONS MUST BE VERIFIED THROUGH AN EXTENSIVE TEST PROGRAM.

• ONE SIGNIFICANT LESSON OF PREVIOUS ISS IMPLEMENTATION IS THAT TESTING IN RELEVANT ENVIRONMENTS OVER THE REQUIRED SENSOR LIFE IS MANDATORY

• FIND THE ISSUES ON THE GROUND OR LAB AND NOT AFTER IT HAS BEEN DEPLOYED ON THE VEHICLE IN SPACE

• TEST TO FAILURE AND ANALYZE THE FAILURE IF POSSIBLE
WHITE SANDS TEST FACILITY O2 SENSOR TESTING

- TESTING OCCURRED SIDE BY SIDE WITH EXISTING ISS SENSOR SYSTEMS FOR ISS ENVIRONMENTAL MONITORING AT WHITE SANDS TEST FACILITY
- TESTING OCCURRED OVER A RANGE OF PRESSURES AND O2 CONCENTRATIONS INTEGRATED WITH ELECTRONICS AND PRESSURE COMPENSATION
- REPEATED CYCLES OVER SEVERAL TEST PERIODS APPROXIMATED ~8 YEARS OF ISS OPERATION
- ACCURACY OF CALIBRATION, REPEATABILITY OF DATA, RESPONSE TIME WERE MAJOR OF EVALUATION CRITERIA
  - THIS IS A CRIT 1 (RELATED TO LIFE OF CREW) FUNCTION WITH STRICT CALIBRATION/PERFORMANCE REQUIREMENTS (+/-0.8%)
- MAJOR FINDING: SENSOR FAILURE MECHANISMS IDENTIFIED

NAFION based oxygen sensor (left) and sensors during piggyback testing with NASA CSA-O2 systems
PROGRAM RESULTS: ROOM TEMPERATURE O2 SENSORS
CHANGES IN RESPONSE TO WHITE SANDS TESTING

- 2.5 YEARS OF LIFE DURING BENCH TESTING/8 YEARS
  OF EQUIVALENT PRESSURE TESTING
- ROOM TEMPERATURE O2 SENSORS VIABLE FOR CRIT 1
  ISS FUNCTION
  - SENSOR RESPONSE TIME, SENSITIVITY,
    CALIBRATION CAPABILITY
- LIFETIME OF O2 SENSORS WAS DETERMINED/PRIMARY
  GOAL OF PROJECT
  - FAILURE MODE WAS THAT THE O2 SENSORS
    STARTED DRIFTING OUTSIDE OF ALLOWSABLE
    CRIT 1 TOLERANCES FOR O2 PERCENTAGE.

Example Failure
Mechanism: Diffusion Hole Breakdown

Present Sensor Structure

Sputtered Based Three Electrode System

Batch Processed MEMS based Packaged Sensor

TESTING AT WHITE SANDS
GRC Instrumentation For Space
Designed, Built, Programmed & Qualified In-House

• 1996 – Mars Pathfinder: Electronic hardware for Sojourner
  – Materials Adherence Experiment Quartz Crystal Microbalance
  – Microprocessor based dust mass instrument with GRC specified, modified and characterized sensor
  – Electronics performed flawlessly determining that sensor saturated during unplanned secondary egress maneuver by JPL
GRC Instrumentation For Space
Designed, Built, Programmed & Qualified In-House

- 2001 – Mars In-Situ Propellant Precursor (MIPP): Mars Array Technology Experiment and Dust Accumulation and Removal Technology (MATE & DART)
  - Complete MIPP experiment top plate and circuit board set development to characterize multiple solar cell technologies and perform dust characterization and mitigation.
GRC Instrumentation For Space
Designed, Built, Programmed & Qualified In-House

Forward Technology Solar Cell Experiment (FTSCE) as part of 5th Materials on the International Space Station Experiment (MISSE-5)
Attached to the P6 Solar Panel Strut
GRC Instrumentation For Space
Designed, Built, Programmed & Qualified In-House

• July 2005 – Forward Technology Solar Cell Experiment (FTSCE) as part of 5th Materials on the International Space Station Experiment (MISSE-5)

  – First Ever Active Experiment in MISSE Series
  – 36 present and new solar cell technologies being exercised while directly exposed to Low Earth Orbit
  – Various temperature, sun position and radiometry sensors
  – Operating through ground command radio link and autonomously through internal schedule, sun position and temperature
  – After a successful one year mission, FTSCE was returned to Earth and will be refurbished at GRC and flown again on MISSE-7
GRC Mobile Sensor and Instrumentation Platforms

First Generation sensor platform:
• video
• packetized one way command link

Second Generation size shrink
• with two way command and data path
• real time video
• multi-agent slotted network protocol

Telerobotics
• Sensor Platform Area Network (SPAN)
• two agent control over the Internet
• streaming video
• each agent owns state vector of the other

Group Awareness and Behavior
• sensing the presence and position of other robot(s)
• near field sensing and communications channel
• mimics weakly electric fish
Highlander Lunar Rover Initiative

“Cratos” - Lunar Rover Test Mule Operating at NASA GRC

NASA GRC and The Robotics Institute at Carnegie Mellon University Co-Developing Tracked Rovers Capable of Autonomous Descent and Ascent of Crater Walls

Carnegie Mellon Highlander Design Benefits From Instrumentation and Motion Control Electronics and Algorithms Designed, Built and Tested in Cratos at GRC.

CMU Highlander Rover
Whegs™ robots combine the advantages of combining wheels and legs and mimic the tripod gate used by the common Cockroach. Whegs allow a robot to climb over objects that are much higher than could be overcome using wheels.

Whegs™ can also be hardened to swim on or under water and would make superb lake bottom crawlers.

GRC and CWRU are hardening Whegs™ as potential Lunar, Mars and terrestrial sensor platforms.
HOW DOES ONE MAKE SENSE OF ALL THIS SENSOR DATA QUALIFICATION
Sensor Implementation Considerations

For Ares I Crew Launch Vehicle

• Each abort algorithm requires detection and confirmation of the condition
  
  ➢ Requires multiple hardware redundant measurements of the same property (homogeneous sensors)
  
  OR
  
  ➢ Require analytical redundancy with correlation of sensors measuring different, but related properties (heterogeneous sensors)

• Flight Computer Software must provide data qualification on all flight critical sensors.
  
  ➢ Due to design constraints (e.g. cost, weight and heritage hardware) utilization of existing homogeneous and heterogeneous redundant sensors may be required
Data Qualification

- Provides control and diagnostic systems with qualified sensor information
  - Reduces probability that actions or operational decisions will be based upon faulty information
  - Increases confidence in measurements from unfailed sensors

- Supports Launch Commit Criteria flexibility by identifying sensor faults versus system failures

- Screen faulty sensor data in performance data on-board prior to compression and transmission to ensure accurate information

- Software solution – requires no additional mass/weight
  - Potential benefit of additional redundancy (through analytical relationships) without weight/complexity of additional sensors.
  - Adding more sensors may not be an option.
Solution ⇒ Sensor Data Qualification System (SDQS)

- An algorithmic approach for continuously monitoring/analyzing sensor data at the flight computer to determine whether or not data values are within normal operating limits.
  - Sensor data is considered qualified if the SDQS determines that values are within the bounds of normal operation for a given sensor.
  - Sensor data fails qualification if the SDQS determines that values are outside the bounds of normal operation for a given sensor over a set time period.
- Data qualification performed in three stages:
  
  **Individual Sensor Validation**
  - Screening/filtering for gross faults:
    - Amplitude Limits
    - Rate-of-change Limits
    - Noise Limits

  **Multi-Sensor Validation**
  - Redundancy-based analysis:
    - Hardware – *homogenous comparison of redundant sensors*
    - Analytical – *heterogeneous comparison physically dependent sensors*

  **Decision Logic**
  - Determine whether sensor data is valid or invalid based on available info and analysis.
Types of Sensor Failure Modes Targeted

- **Hard Failure** (open/short circuit)
- **Time Drift Failure** (thermal/resistance change)
- **Intermittent-Binary** (loose connector)
- **Intermittent-Filtered** (cracked solder joint)
- **Iced-Up Failure** (sensor value locked)

**Legend**
- Good Sensor
- Failed Sensor
Sensor Data Qualification System (SDQS) Functional Flow

**Initialization**
- Initiate SDQS
- Obtain Sensor Data

**DETECTION OF FAULTS IN SENSOR DATA**

- **Reasonableness Checks (Gross Failure Detection)**
  - Perform Limit Checks
  - Increment or Reset Limit Check Fault Counters
  - Perform Rate Checks
  - Increment or Reset Rate Check Fault Counters
  - Perform Noise Checks
  - Increment of Reset Noise Check Fault Counters

- **Redundancy Estimation and Detection**
  - Perform Redundant Channel Checks
  - Increment or Reset RCC Fault Counters
  - Perform Analytical Redundancy Checks
  - Increment of Reset ARC Fault Counters

**Mission-level Decision Algorithm**
- Query Fault Counters to Qualify/Disqualify Sensor Data
- Set Data Quality Indicators (DQI) in Sensor Data Table

**Cycle-level Detection Algorithms**
- Determine Mission Phase, Subsystems Phase,
The **PHALT** System was developed for use in rapid prototyping and testing of diagnostic algorithms in real-time hardware

- **Portable**  
  Laptop (development platform) and industrial, rack-mount PC (real-time target) provide portability to support on-the-road demonstrations and real-time testing

- **Diagnostic Algorithms**  
  - Currently limited to data validation  
  - Capability to add a variety of diagnostic & prognostic health management algorithms

- **Test**  
  - Matlab/Simulink xPC software provides capability for rapid prototyping and seamless generation of real-time applications.  
  - Industrial PC with real-time I/O supports real-time testing of algorithms with broad spectrum of available test rigs.
PHALT System Demonstration Results

Data Qualification Testbed Demonstrations

- PHALT System tied onto the Electrical Power System (EPS) Power Distribution Unit (PDU) Controller Area Network (CAN) Bus Card
  - 25 of 26 Simulated Sensor failures were caught by the qualification network being demonstrated.
  - The Undetected Failure Was a Drift That Would Have Been Caught if Allowed to Continue.
- PHALT System implemented within a Combustion Valve Test Rig
  - Real-time hardware sensor failures produced
  - Conducted demonstration of sensor failures with closed-loop control sensors
  - Demonstrated viability of software approach
  - Tests and evaluate of detection software are on-going
TRANSITION OF SENSOR SYSTEMS TO FLIGHT:
SOME AREAS OF CONSIDERATION

• DEVELOPMENT OF A FULL LIFE-CYCLE PLAN FOR THE PRODUCT IS FUNDAMENTAL
  ➢ TEAM COMPOSED OF THE PRODUCT DEVELOPER, THE END-USER, AND FLIGHT
    VEHICLE AND/OR GROUND SUPPORT. EXPERTS FROM SAFETY, RELIABILITY,
    LOGISTICS, SYSTEM INTEGRATION AND PROJECT MANAGEMENT.

• DETAILED SET OF REQUIREMENTS CRITICAL VERY EARLY IN THE PROCESS TO
  AVOID UNNECESSARY DELAYS AND/OR COSTLY REDESIGNS. INCLUDED ARE:
  ➢ PERFORMANCE CONSIDERATIONS
  ➢ PHYSICAL CONSIDERATIONS
  ➢ ENVIRONMENTAL CONSIDERATIONS
  ➢ SAFETY AND RELIABILITY CONSIDERATIONS

• FAILURE MODES EVALUATION ANALYSIS CONDUCTED DURING THE QUALIFICATION
  OF THE PRODUCT.

• EXTENSIVE TESTING EVEN TO FAILURE
SYSTEM LEVEL SUGGESTIONS

• SENSORS SYSTEMS BE INCLUDED INTO THE VEHICLE IN THE DESIGN PHASE.

• STUDY THE VEHICLE SYSTEM TO DETERMINE OPERATIONAL FUNCTION AND CRITICALITY OF VARIOUS SENSOR SYSTEMS AND HOW TO OPTIMIZE CROSS FUNCTIONALITIES.

• INSTRUMENT THE VEHICLE SYSTEM TO ALLOW MEASUREMENTS TO ENABLE DAMAGE/DEGRADATION PREDICTION AT A LEVEL TO ALLOW AUTONOMOUS OPERATION.

• DEMONSTRATE SENSOR RELIABILITY AND DURABILITY BEFORE INCLUSION OF SENSOR SYSTEM INTO VEHICLE.

• PERFORM SENSOR MEASUREMENTS TO OPTIMIZE MEASUREMENT OF MULTIPLE PARAMETERS SIMULTANEOUSLY TO IMPROVE FULL-FIELD SYSTEM INFORMATION AND MEASUREMENT RELIABILITY.

• DEVELOP SENSOR SYSTEMS WHICH INCLUDE INTEGRATED INTELLIGENCE WHILE MINIMIZING SIZE, WEIGHT, AND POWER CONSUMPTION.

• AT MINIMUM, CRIT 1 SYSTEMS, I.E. THOSE WHOSE FUNCTION CAN AFFECT LOSS OF CREW AND/OR VEHICLE, SHOULD BE MONITORED NO MATTER THE EXTREME CONDITION INHERENT IN SUCH MONITORING.
FUTURE DIRECTIONS

NANOTECHNOLOGY
NANOTECHNOLOGY DEVELOPMENT
NANO DIMENSIONAL CONTROL PREVALENT IN CHEM/BIO SENSORS

• NANO CONTROL OF CHEMICAL SENSOR STRUCTURES STRONGLY PREFERRED EVEN IF SENSOR ISN’T LABELED A “NANO SENSOR”
  - WE ARE MEASURING VARYING NUMBERS OF MOLECULES
• IF NANOTECHNOLOGY ALREADY PRESENT IN CHEM/BIO SENSOR DEVELOPMENT, THEN:
  - WHAT STAYS THE SAME AND WHAT’S NEW?
  - WHAT ARE THE CHALLENGES IN NANOTECHNOLOGY DEVELOPMENT?
  - WHAT IS THE ROLE/ADVANTAGE OF NANO TECHNOLOGY

SAME

• APPLICATIONS DON’T CARE THAT IT IS NANO, NEED IMPROVED CAPABILITIES
• STANDARD SENSOR TECHNOLOGY REQUIREMENTS, POTENTIAL, AND DIRECTIONS SET BY THE ADVENT OF MICROTENNOLOGY REMAIN CONSTANT
• SENSITIVITY, SELECTIVITY, STABILITY, RESPONSE TIME, TAILOR FOR THE APPLICATION, “LICK AND STICK”, ETC.
• PACKAGING STILL SIGNIFICANT COMPONENT OF SYSTEM
• AS WITH MICRO, CAN ONLY GO AS FAR AS THE SUPPORTING TECHNOLOGIES
• MULTIPLE SENSOR PLATFORMS MAY STILL BE NECESSARY DEPENDING ON THE APPLICATION/ENVIRONMENT

TARGETED TECHNOLOGY DEVELOPMENT
• MICRO-NANO CONTACT FORMATION
• NANOMATERIAL STRUCUTURE CONTROL
• OTHER NANO OXIDE MATERIALS
EXAMPLE NANOTECHNOLOGY CHALLENGE: MICRO-NANO CONTACT FORMATION

- NO MATTER HOW GOOD THE SENSOR, IF YOU CANNOT MAKE CONTACT WITH IT, THEN IT WILL NOT BE INEFFECTIVE
- MICRO-NANO INTEGRATION/CONTACTS
  - MAJOR QUESTION FOR NANOSTRUCTURED BASED SENSORS: HOW ARE THE NANOSTRUCTURED MATERIALS INTEGRATED INTO A MICROSTRUCTURES
- MANUAL METHODS GENERALLY INVOLVE REPEATABILITY ISSUES E.G.
- BASIC WORK ON-GOING TO IMPROVE MICRO-NANO CONTACTS E.G. USE OF DIELECTROPHORESIS TO ALIGN NANOSTRUCTURES
- BRING THE LEVEL OF PROCESS CONTROL PRESENT IN MICROSYSTEMS TO NANOTECHNOLOGY

NANOSTRUCTURE FABRICATED BY THERMAL EVAPORATION-CONDENSATION PROCESS.

NANORODS CONTACTED WITH THE SUBSTRATE VIA A SILVER EPOXY

ZINC OXIDE NANORODS AFTER DIELECTROPHORESIS ACROSS INTERDIGITATED FINGERS
“LOCK AND KEY” CHEMICAL SENSORS USING NANOSTRUCTURES

- **OBJECTIVE:** DEMONSTRATE THE FUNDAMENTAL ABILITY TO ASSEMBLE THE ULTIMATE “LOCK AND KEY” CHEMICAL SENSOR DETECTION SYSTEM

- **STATE OF THE ART:**
  
  Limited Chemical Selectivity by use “Lock and Key” Approach
  
  Many Species, Complex Structures Lead to Limited Ability For Species Identification
  
  Nose Approaches necessary to attempt to understand environment but still limited in species identification: multispecies identification, closely related species, significant false positives

- **TECHNICALLY ADDRESS THE FUNDAMENTAL QUESTION “WHAT IS NANO GOOD FOR?” IN THE AREA OF CHEMICAL SENSORS:**
  
  - Not small nano structures for billion molecule measurements/ in such applications may consider thin films or alternate sensor platforms
  
  - Instead use nanostructures for detection on molecular level

- **ARRANGE THE CHEMICAL SENSOR STRUCTURE TO “FIT” THE MOLECULE IN QUESTION**

- **VERIFY THE PRESENCE OF THE MOLECULE WITH AN ELECTROCHEMICAL SIGNATURE**

- **FABRICATE “DESIGNER” CHEMICAL SENSORS**
SENSORS HAVE WIDE VARIETY OF APPLICATIONS BUT CANNOT WORK IN EVERY ENVIRONMENT

RIGHT SENSOR FOR RIGHT APPLICATION

H₂ SENSOR OPERATION UNDER WATER
SUMMARY

- Aerospace applications require a range of sensing technologies.
- A range sensor and sensor system technology being developed to meet these needs using:
  - Microfabrication and micromachining technology
  - Smart sensor systems
- Technology best applied with strong interaction with user/tailor sensor for needs of application/supporting technologies mandatory.
- Supporting technologies necessary.
- Drive system intelligence to the sensor level.
- Long-term: intelligent systems
  - Reliability
  - Redundancy
  - Orthogonality
  - Cross-correlation
- Sensor implementation
  - A number of barriers
  - A team approach supported by testing
- Nanotechnology
  - Significant promise but technology barriers exist
  - Long-term fully enable “lick and stick”
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